



Figure 1. Visitors organized by CPCA.

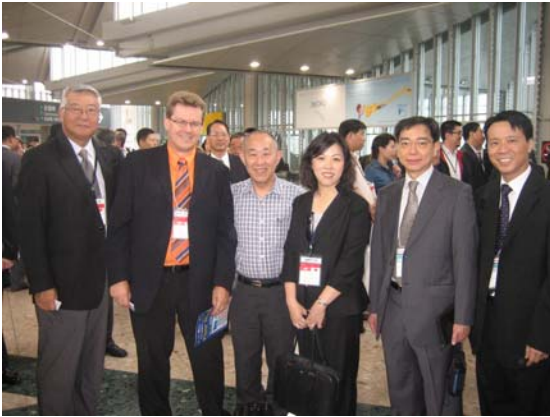


Figure 2. HKPCA visitors.



Figure 3. The JPCA reception.



Figure 4. Mr. Kumar (CPCA), Mr. Weinhold and Mr. Rosario (EIPC). (from left to right)



Figure 5. Dr. Nakahara, Mr. Vousten and Mr. Berkel of Ruwel AG. (from left to right)



Figure 6. Richard McCann (MacDermid), Michael Moisan (TTM), Dr. Nakahara and Hardeep Herr (ECT). (from left to right)



Figure 7. CMK showed an example of wafer level package integration for watch module.

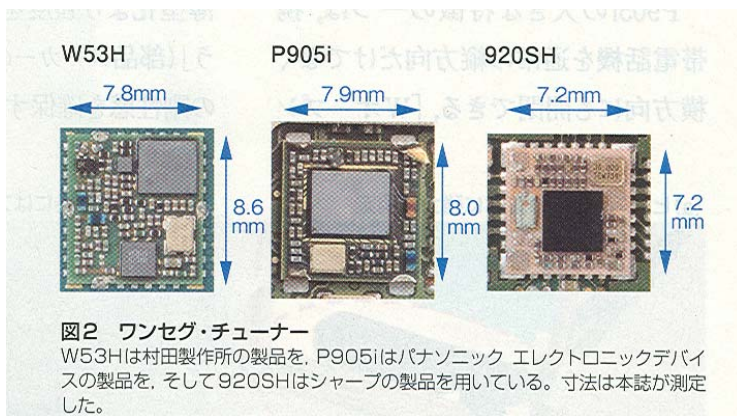


Figure 8. One segment tuner modules for cell phones (Toppan-NEC).



Figure 9. Paragon 8800 with automated loader.



Figure 10. DiIMPACT DXP-3502 for PSR by ORC.



Figure 11. IMPRES by Fuji Film.

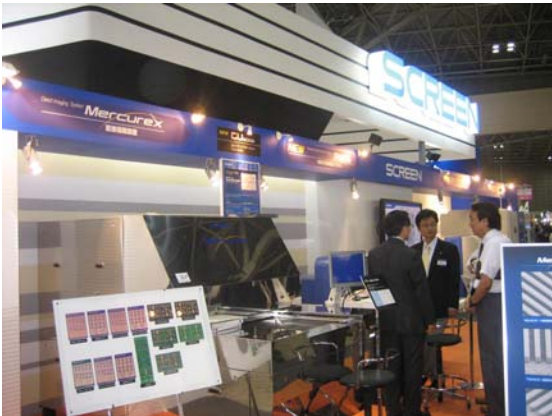


Figure 12. Mercurex by DNS.



Figure 13. HVM's "Digital Exposure" machine.



Figure 14. HVM 4-Table CO₂ drilling machine.



Figure 15. 190% efficiency with 50% more space.

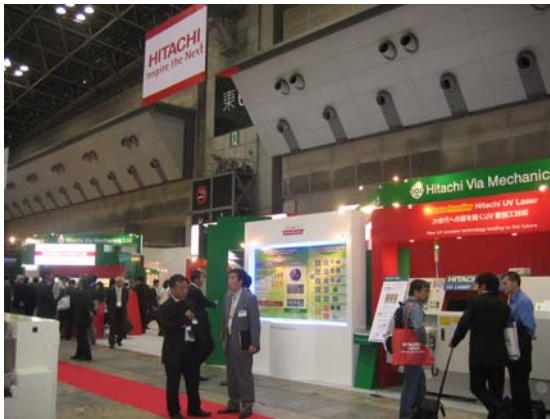


Figure 16. HVM advertising UV/YAG laser.



Figure 17. Mitsubishi Electric 4-Beam CO₂ laser.

ML605GTWII-5150U 特長紹介
優れた銅ダイレクト加工性能

ML605GTWII-5150U Features Leading copper direct processing performance

**銅ダイレクト加工のパイオニア、
 全世界で500台以上の加工実績**

The pioneer of copper direct processing, proves its processing performance in more than 500 systems installed around the world

特長 / Features

- 多様な表面処理に対して安定した銅ダイレクト加工が可能。三菱電機の銅ダイレクト加工は黒化処理に限定されません。
 Stable copper direct processing possible on various surface treatment. Mitsubishi's copper direct processing is not limited to blackening treatment.
- 自社製の高ピーク発振器が高品質な銅ダイレクト加工を実現します。
 Mitsubishi's original high-peak high-power oscillator realizes stable and high-quality copper direct processing.



Black oxide



CZ treatment



Brown treatment



DL treatment

MITSUBISHI
Changes for the Better

Figure 18. Mitsubishi Model ML605GTWII-5150U for CO₂ Copper Direct.

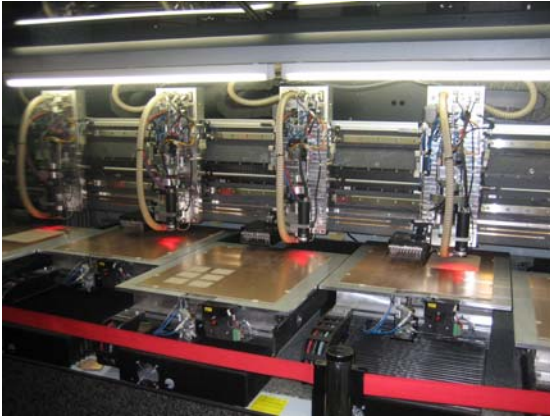


Figure 19. The Schmol version (router) of the independent axis drive machine.



Figure 20. Six-spindle HVM version of the independent axis drive machine.



Figure 21. Micro Craft model MJ6151D1.

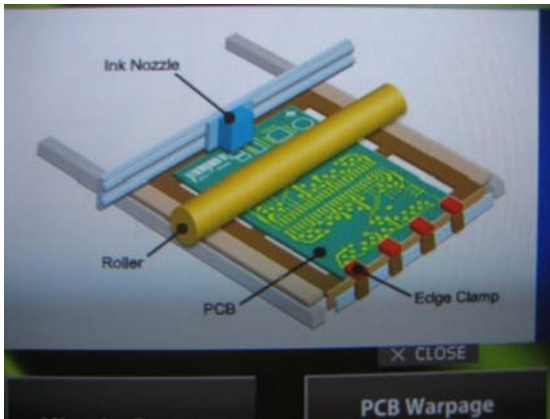


Figure 22. Panel flattening scheme.

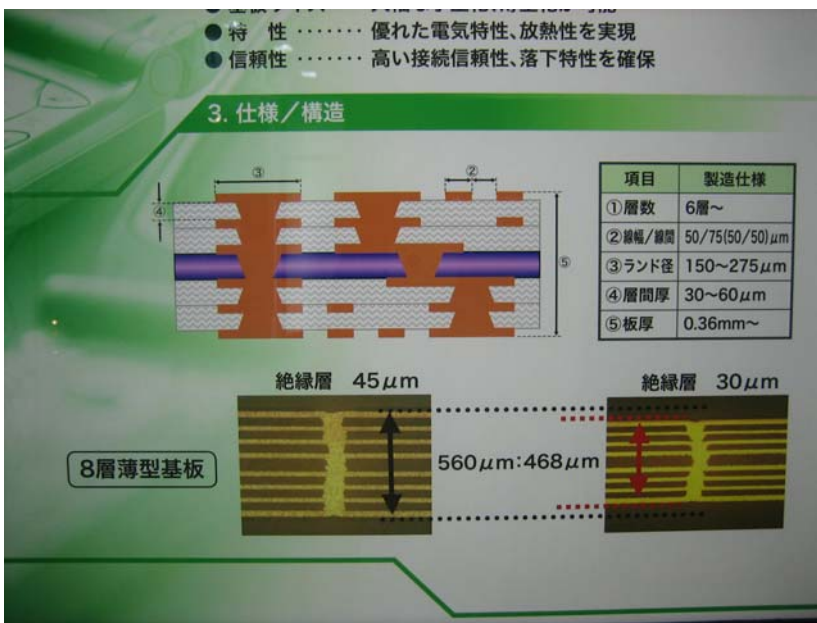


Figure 23. Cross-section of 8L FVSS boards with L/S=50/50 μm (Ibiden).

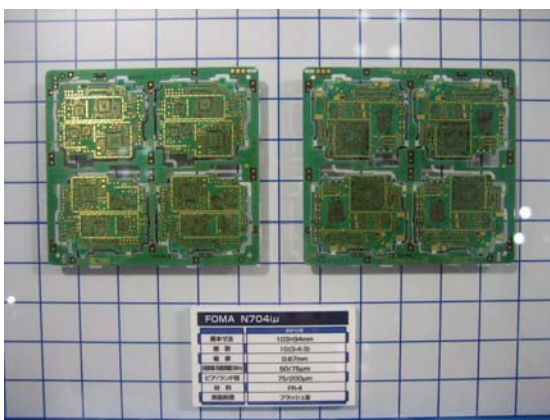


Figure 24. 3+4+3 Cell Phone board with 50/50 μm (Toppan-NEC).



Figure 25. 1+8+1 for Panasonic NB “Lets Note”(Toppan-NEC).

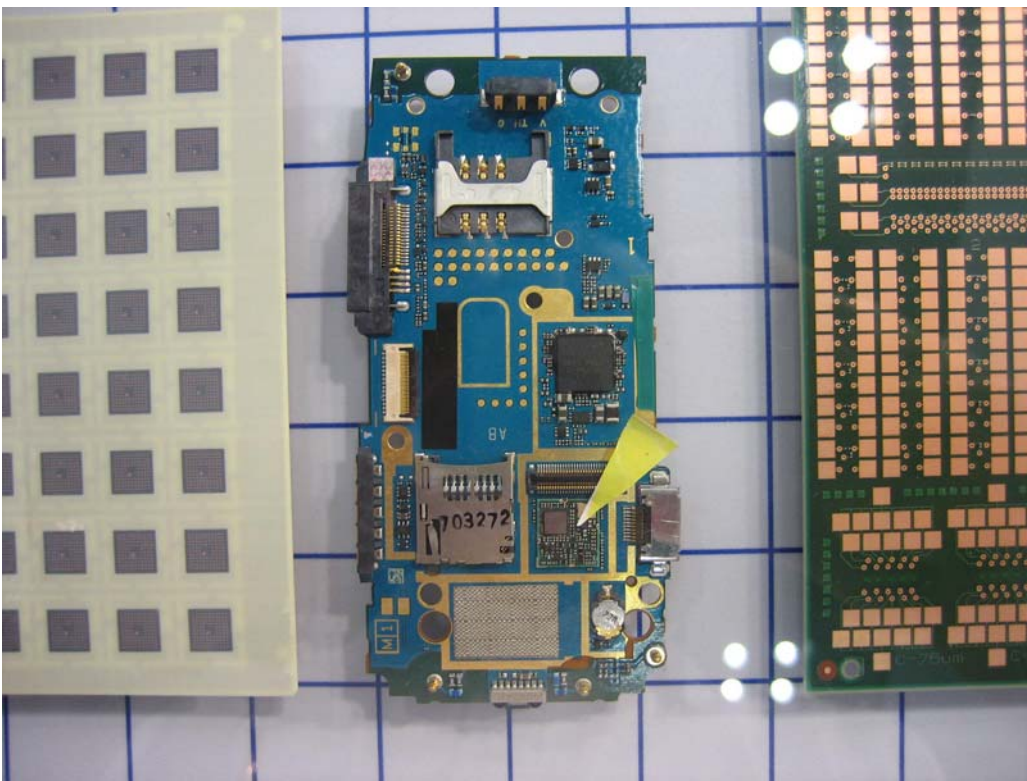


Figure 26. One-Segment TV Tuner (2+2+2) attached to motherboard for cell phone.

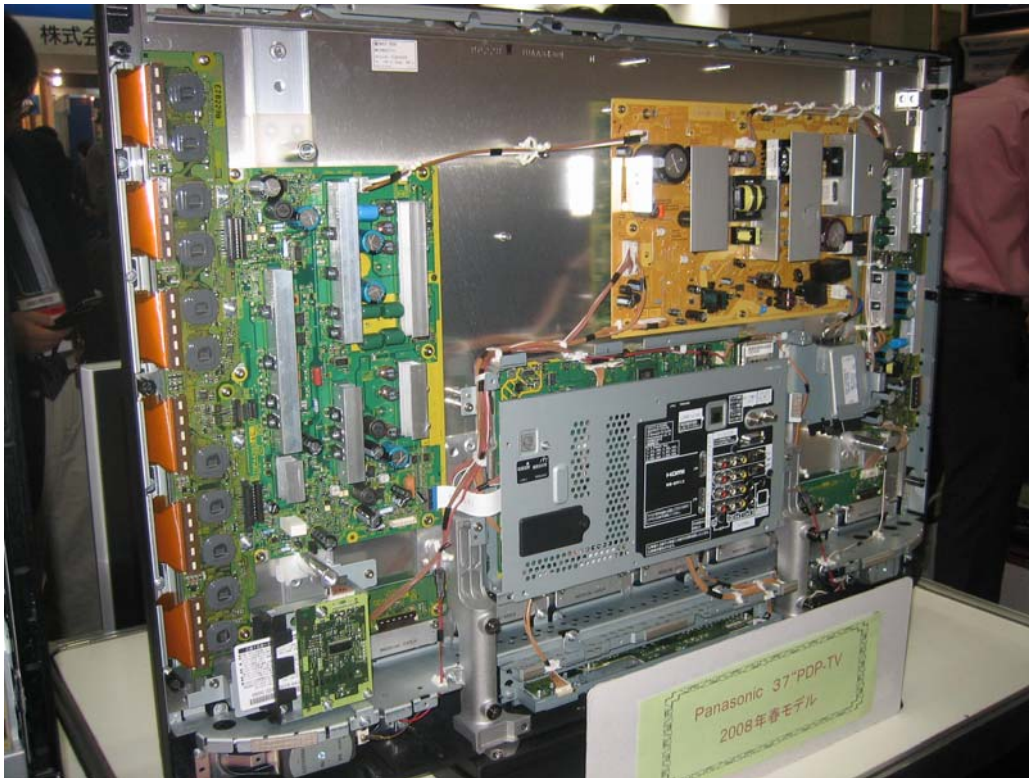


Figure 27. 37" PDP TV (Panasonic) Total PCB: 1.2m², estimated worth \$40/set (DS FR-4. Tuner board, SS FR-1 Power Supply, 6L FR-4 Main board, 2L Fr-4 LCD display etc).



Figure 28. Current Design Rules.



Figure 29. Technology Trend of Build-Up IC Substrate.